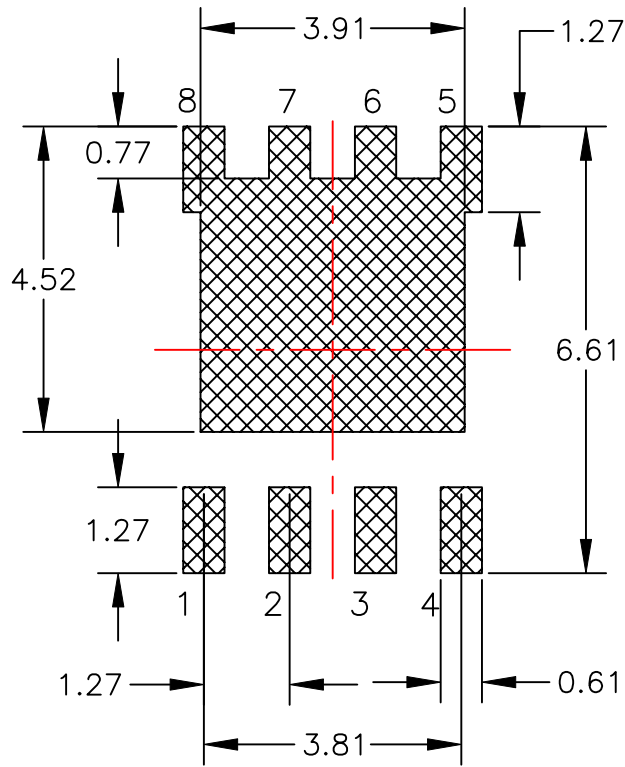
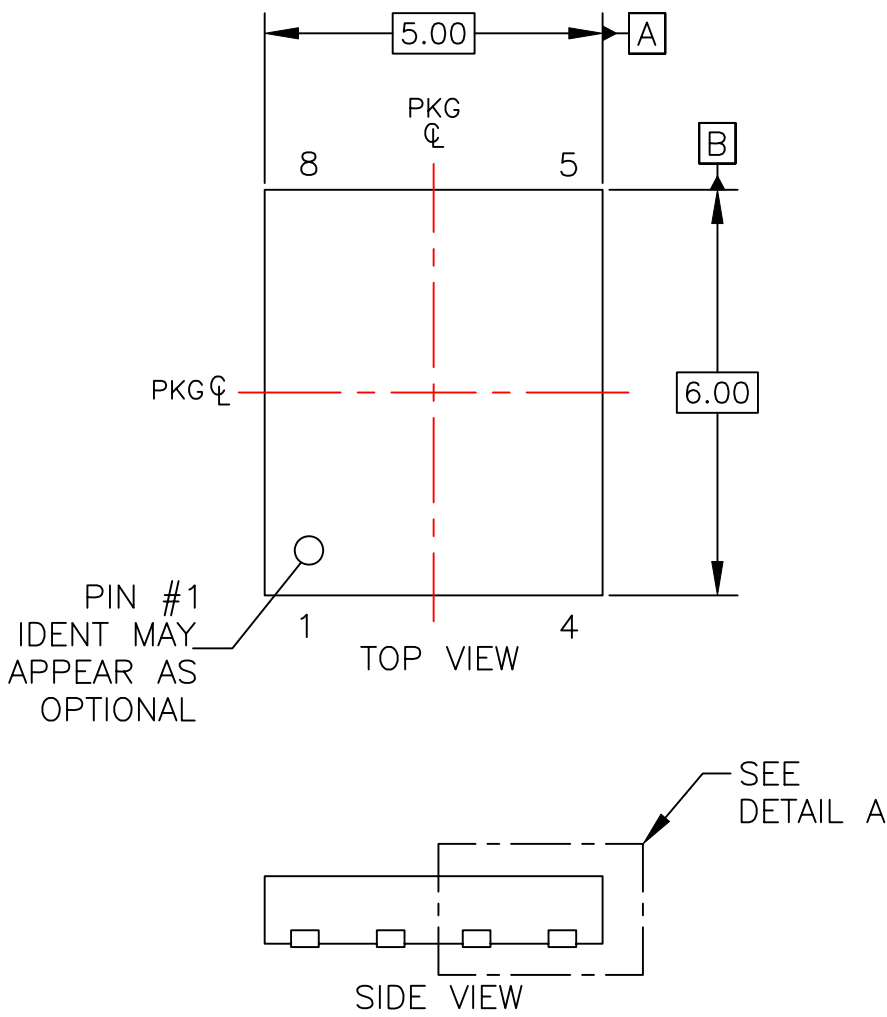
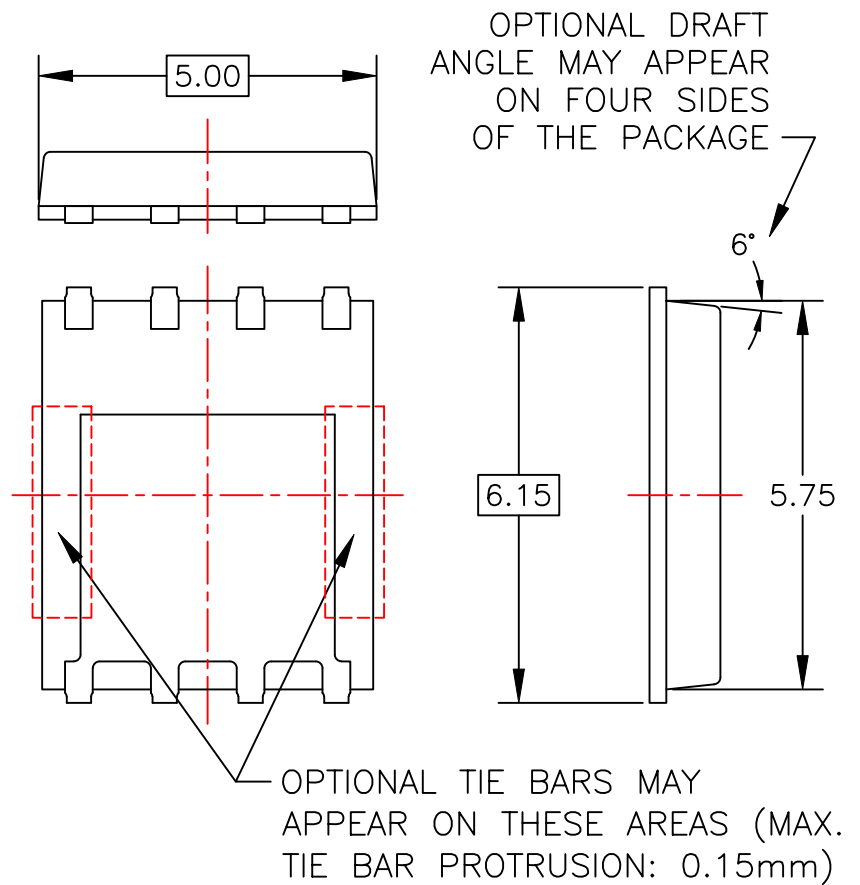
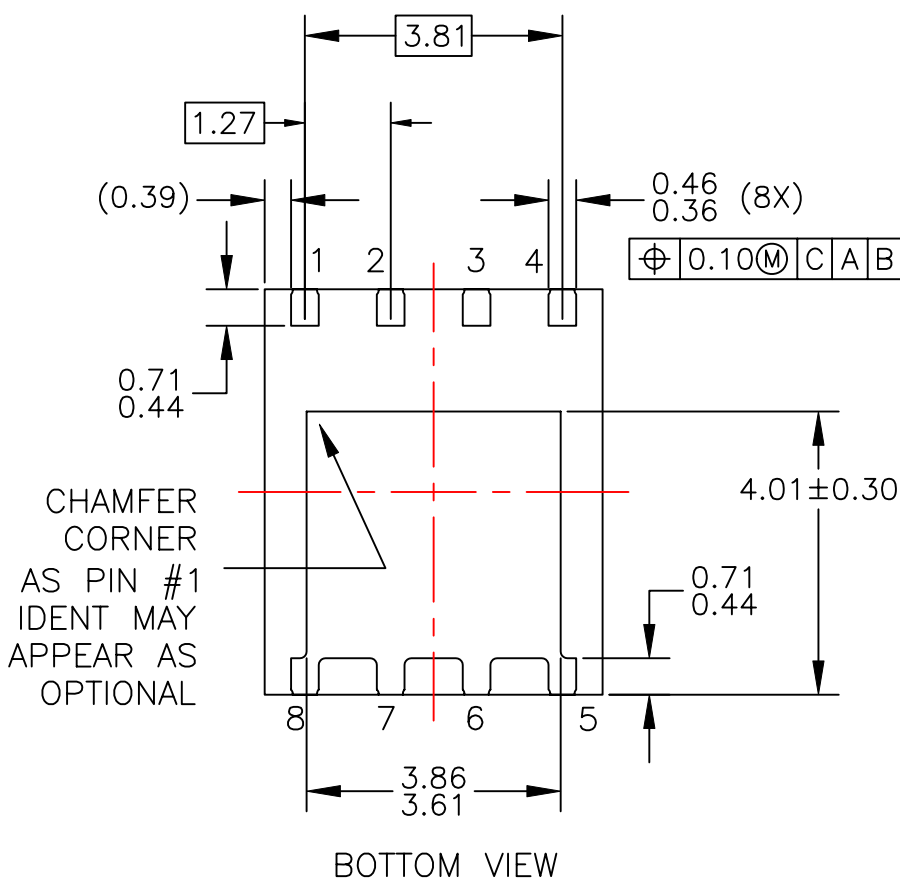


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REVISIONS			
LTR	DESCRIPTION	DATE	NAME/SITE
3	ADD NO. OF REPETITION TO LD WID DIM	17SEPT2008	CBE/CB
4	CHG "E" DIM FR 6.00 BSC TO 6.15 BSC; CHG LD THICKNESS FR 0.20 TO 0.25	24APR2009	CBE/CB



LAND PATTERN RECOMMENDATION

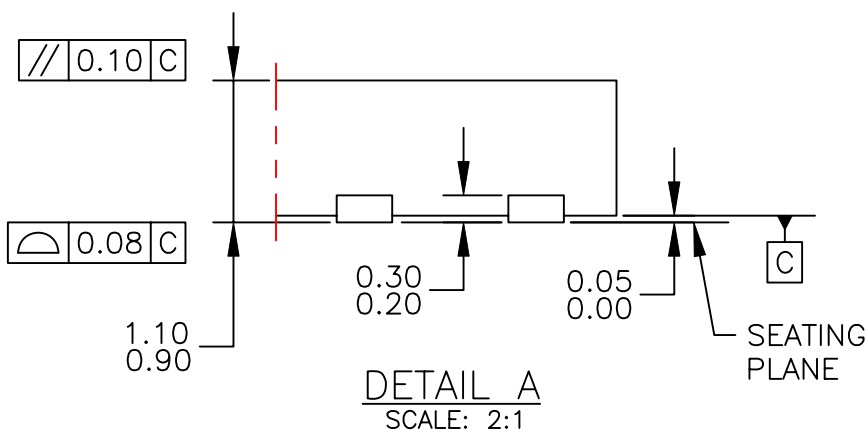


OPTIONAL DRAFT ANGLE MAY APPEAR ON FOUR SIDES OF THE PACKAGE

OPTIONAL TIE BARS MAY APPEAR ON THESE AREAS (MAX. TIE BAR PROTRUSION: 0.15mm)

NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. AA, DATED OCTOBER 2002.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: PQFN08AREV4



DETAIL A  
SCALE: 2:1

APPROVALS		DATE	FAIRCHILD SEMICONDUCTOR™	
DRAWN: J.U. COMPARATIVO JR.		24APR2009	8LD, PQFN, JEDEC MO-240 AA, 5.0X6.0MM	
CHECKED: C.B. ESTACIO				
APPROVED: M.R. GESTOLE				
C.N. TANGPUZ			SCALE 1:1	SIZE N/A
PROJECTION			DRAWING NUMBER MKT-PQFN08A	REV 4
INCH [MM]			FORMERLY: N/A	SHEET : 1 OF 1